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Details

Product Status	Active
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I ² C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Cap Sense, POR, PWM, WDT
Number of I/O	16
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-QFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f991-c-gmr

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C8051F99x-C8051F98x

1. System Overview

C8051F99x-C8051F98x devices are fully integrated mixed-signal system-on-a-chip MCUs. Highlighted features are listed below. Refer to Table 2.1 for specific product feature selection and part ordering numbers.

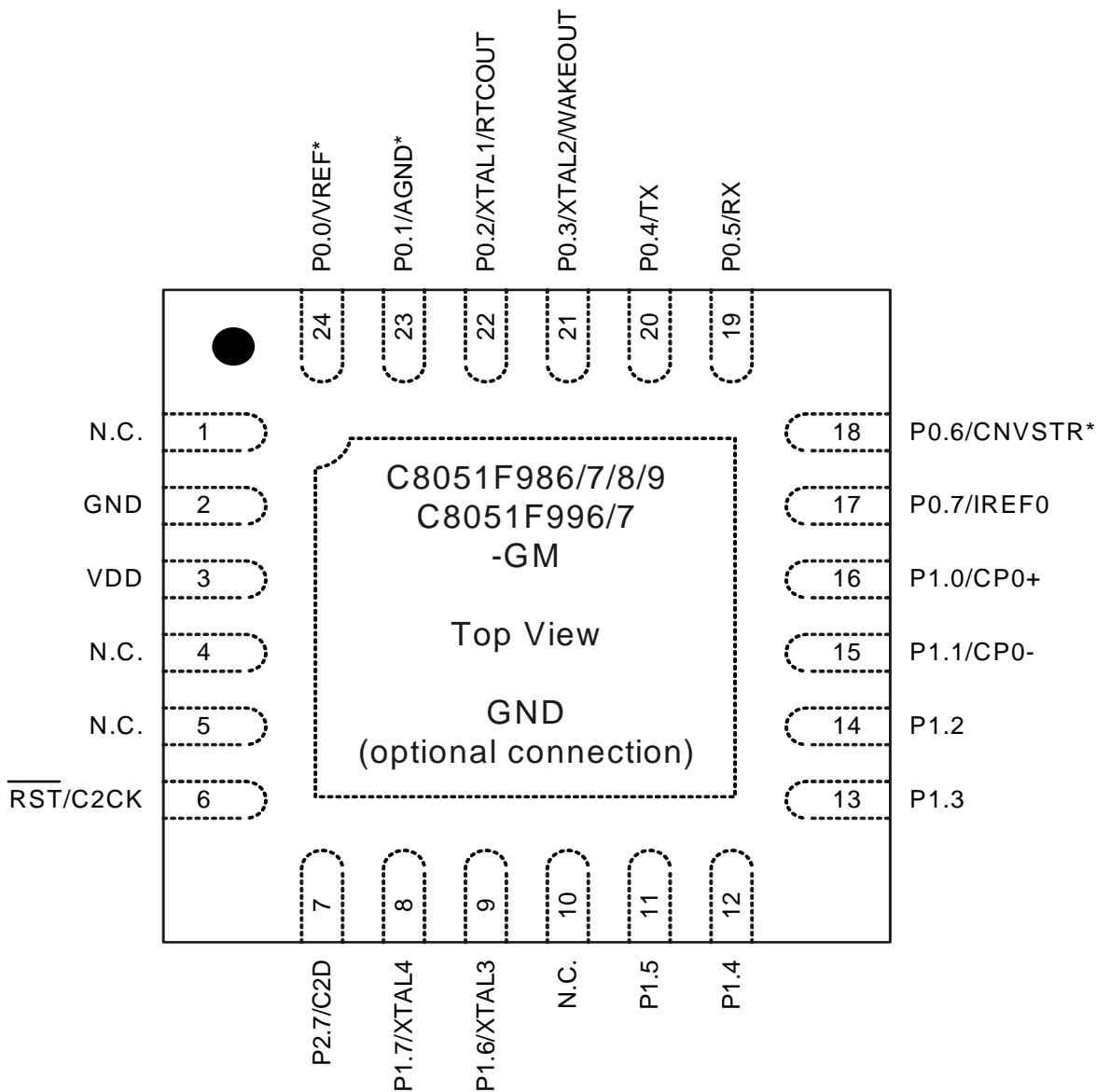
- Ultra low power consumption in active and sleep modes.
- High-speed pipelined 8051-compatible microcontroller core (up to 25 MIPS)
- In-system, full-speed, non-intrusive debug interface (on-chip)
- 10-bit 300 ksps or 12-bit 75 ksps single-ended ADC with analog multiplexer
- 6-bit programmable current reference (resolution can be increased with PWM)
- Precision programmable 24.5 MHz internal oscillator with spread spectrum technology.
- 8 kB, 4 kB, or 2 kB of on-chip Flash memory
- 512 bytes of on-chip RAM
- SMBus/I²C, Enhanced UART, and Enhanced SPI serial interfaces implemented in hardware
- Four general-purpose 16-bit timers
- Programmable counter/timer array (PCA) with three capture/compare modules and watchdog timer function
- On-chip power-on reset, V_{DD} monitor, and temperature sensor
- One on-chip voltage comparator
- Up to 14 Capacitive Touch Inputs
- Up to 17 Port I/O

With on-chip power-on reset, V_{DD} monitor, watchdog timer, and clock oscillator, the C8051F99x-C8051F98x devices are truly stand-alone system-on-a-chip solutions. The Flash memory can be reprogrammed even in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. User software has complete control of all peripherals, and may individually shut down any or all peripherals for power savings.

The on-chip Silicon Labs 2-Wire (C2) Development Interface allows non-intrusive (uses no on-chip resources), full speed, in-circuit debugging using the production MCU installed in the final application. This debug logic supports inspection and modification of memory and registers, setting breakpoints, single stepping, run and halt commands. All analog and digital peripherals are fully functional while debugging using C2. The two C2 interface pins can be shared with user functions, allowing in-system debugging without occupying package pins.

Each device is specified for 1.8 to 3.6 V operation over the industrial temperature range (–40 to +85 °C). The Port I/O and RST pins are powered from the supply voltage. The C8051F99x-C8051F98x devices are available in 20-pin or 24-pin QFN or 24-pin QSOP packages. All package options are lead-free and RoHS compliant. See Table 2.1 for ordering information. Block diagrams are included in Figure 1.1 through Figure 1.9.

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***Note:** Signal only available on 'F986, 'F988, and 'F996 devices.

Figure 3.2. QFN-24 Pinout Diagram (Top View)

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Table 4.13. IREF0 Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, -40 to +85 °C, unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Static Performance					
Resolution		6			bits
Output Compliance Range	Low Power Mode, Source	0	—	$V_{DD} - 0.4$	V
	High Current Mode, Source	0	—	$V_{DD} - 0.8$	
	Low Power Mode, Sink	0.3	—	V_{DD}	
	High Current Mode, Sink	0.8	—	V_{DD}	
Integral Nonlinearity		—	$<\pm 0.2$	± 1.0	LSB
Differential Nonlinearity		—	$<\pm 0.2$	± 1.0	LSB
Offset Error		—	$<\pm 0.1$	± 0.5	LSB
Full Scale Error	Low Power Mode, Source	—	—	± 5	%
	High Current Mode, Source	—	—	± 6	%
	Low Power Mode, Sink	—	—	± 8	%
	High Current Mode, Sink	—	—	± 8	%
Absolute Current Error	Low Power Mode Sourcing 20 μ A	—	$<\pm 1$	± 3	%
Dynamic Performance					
Output Settling Time to 1/2 LSB		—	300	—	ns
Startup Time		—	1	—	μ s
Power Consumption					
Net Power Supply Current (V_{DD} supplied to IREF0 minus any output source current)	Low Power Mode, Source				
	IREF0DAT = 000001	—	10	—	μ A
	IREF0DAT = 111111	—	10	—	μ A
	High Current Mode, Source				
	IREF0DAT = 000001	—	10	—	μ A
	IREF0DAT = 111111	—	10	—	μ A
	Low Power Mode, Sink				
	IREF0DAT = 000001	—	1	—	μ A
	IREF0DAT = 111111	—	11	—	μ A
	High Current Mode, Sink				
	IREF0DAT = 000001	—	12	—	μ A
	IREF0DAT = 111111	—	81	—	μ A
Note: Refer to “PWM Enhanced Mode” on page 91 for information on how to improve IREF0 resolution.					

8.8. Automatic Scanning (Method 1—CS0SMEN = 0)

CS0 can be configured to automatically scan a sequence of contiguous CS0 input channels by configuring and enabling auto-scan. Using auto-scan with the CS0 comparator interrupt enabled allows a system to detect a change in measured capacitance without requiring any additional dedicated MCU resources.

Auto-scan is enabled by setting the CS0 start-of-conversion bits (CS0CF6:4) to 111b. After enabling auto-scan, the starting and ending channels should be set to appropriate values in CS0SS and CS0SE, respectively. Writing to CS0SS when auto-scan is enabled will cause the value written to CS0SS to be copied into CS0MX. After being enabled, writing a 1 to CS0BUSY will start auto-scan conversions. When auto-scan completes the number of conversions defined in the CS0 accumulator bits (CS0CF1:0), auto-scan configures CS0MX to the next sequential port pin configured as an analog input and begins a conversion on that channel. All other pins between CS0SS and CS0SE which are set as analog inputs are grounded during the conversion. This scan sequence continues until CS0MX reaches the ending input channel value defined in CS0SE. After one or more conversions have been taken at this channel, auto-scan configures CS0MX back to the starting input channel. For an example system configured to use auto-scan, please see Figure “8.2 Auto-Scan Example” on page 103.

Note: Auto-scan attempts one conversion on a CS0MX channel regardless of whether that channel's port pin has been configured as an analog input. Auto-scan will also complete the current rotation when the device is halted for debugging.

If auto-scan is enabled when the device enters suspend mode, auto-scan will remain enabled and running. This feature allows the device to wake from suspend through CS0 greater-than comparator event on any configured capacitive sense input included in the auto-scan sequence of inputs.

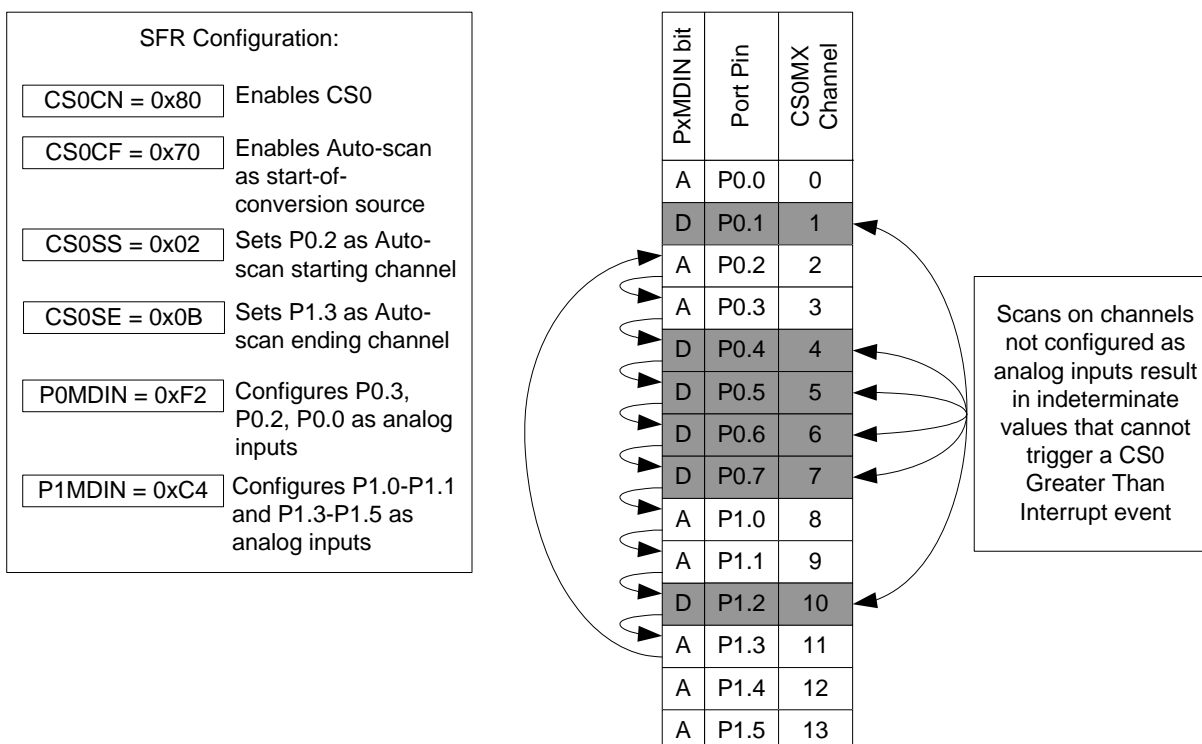


Figure 8.2. Auto-Scan Example

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9.4. CIP-51 Register Descriptions

Following are descriptions of SFRs related to the operation of the CIP-51 System Controller. Reserved bits should not be set to logic 1. Future product versions may use these bits to implement new features in which case the reset value of the bit will be logic 0, selecting the feature's default state. Detailed descriptions of the remaining SFRs are included in the sections of the data sheet associated with their corresponding system function.

SFR Definition 9.1. DPL: Data Pointer Low Byte

Bit	7	6	5	4	3	2	1	0
Name	DPL[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All; SFR Address = 0x82

Bit	Name	Function
7:0	DPL[7:0]	Data Pointer Low. The DPL register is the low byte of the 16-bit DPTR. DPTR is used to access indirectly addressed Flash memory or XRAM.

SFR Definition 9.2. DPH: Data Pointer High Byte

Bit	7	6	5	4	3	2	1	0
Name	DPH[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All; SFR Address = 0x83

Bit	Name	Function
7:0	DPH[7:0]	Data Pointer High. The DPH register is the high byte of the 16-bit DPTR. DPTR is used to access indirectly addressed Flash memory or XRAM.

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space. The addressing mode used by an instruction when accessing locations above 0x7F determines whether the CPU accesses the upper 128 bytes of data memory space or the SFRs. Instructions that use direct addressing will access the SFR space. Instructions using indirect addressing above 0x7F access the upper 128 bytes of data memory. Figure 10.1 illustrates the data memory organization of the C8051F99x-C8051F98x.

10.2.1.1. General Purpose Registers

The lower 32 bytes of data memory, locations 0x00 through 0x1F, may be addressed as four banks of general-purpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in SFR Definition 9.6). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

10.2.1.2. Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit7 of the byte at 0x20 has bit address 0x07. Bit 7 of the byte at 0x2F has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination).

The MCS-51™ assembly language allows an alternate notation for bit addressing of the form XX.B where XX is the byte address and B is the bit position within the byte. For example, the instruction:

```
MOV    C, 22.3h
```

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the Carry flag.

10.2.1.3. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

10.2.2. External RAM

There are 256 bytes of on-chip RAM mapped into the external data memory space. All of these address locations may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using MOVX indirect addressing mode (such as @R1).

14.1.2. Flash Erase Procedure

The Flash memory is organized in 512-byte pages. The erase operation applies to an entire page (setting all bytes in the page to 0xFF). To erase an entire Flash page, perform the following steps:

1. Save current interrupt state and disable interrupts.
2. Set the PSEE bit (register PSCTL).
3. Set the PSWE bit (register PSCTL).
4. Write the first key code to FLKEY: 0xA5.
5. Write the second key code to FLKEY: 0xF1.
6. Using the MOVX instruction, write a data byte to any location within the page to be erased.
7. Clear the PSWE and PSEE bits.
8. Restore previous interrupt state.

Steps 4–6 must be repeated for each 512-byte page to be erased.

Notes:

1. Flash security settings may prevent erasure of some Flash pages, such as the reserved area and the page containing the lock bytes. For a summary of Flash security settings and restrictions affecting Flash erase operations, please see Section “14.3. Security Options” on page 152.
2. 8-bit MOVX instructions cannot be used to erase or write to Flash memory at addresses higher than 0x00FF.

14.1.3. Flash Write Procedure

A write to Flash memory can clear bits to logic 0 but cannot set them; only an erase operation can set bits to logic 1 in Flash. **A byte location to be programmed should be erased before a new value is written.**

The recommended procedure for writing a single byte in Flash is as follows:

1. Save current interrupt state and disable interrupts.
2. Ensure that the Flash byte has been erased (has a value of 0xFF).
3. Set the PSWE bit (register PSCTL).
4. Clear the PSEE bit (register PSCTL).
5. Write the first key code to FLKEY: 0xA5.
6. Write the second key code to FLKEY: 0xF1.
7. Using the MOVX instruction, write a single data byte to the desired location within the 1024-byte sector.
8. Clear the PSWE bit.
9. Restore previous interrupt state.

Steps 5–7 must be repeated for each byte to be written.

Notes:

1. Flash security settings may prevent writes to some areas of Flash, such as the reserved area. For a summary of Flash security settings and restrictions affecting Flash write operations, please see Section “14.3. Security Options” on page 152.
2. 8-bit MOVX instructions cannot be used to erase or write to Flash memory at addresses higher than 0x00FF.

14.2. Non-volatile Data Storage

The Flash memory can be used for non-volatile data storage as well as program code. This allows data such as calibration coefficients to be calculated and stored at run time. Data is written using the MOVX write instruction and read using the MOVC instruction. MOVX read instructions always target XRAM.

SFR Definition 14.4. FLKEY: Flash Lock and Key

Bit	7	6	5	4	3	2	1	0
Name	FLKEY[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All; SFR Address = 0xB7

Bit	Name	Function
7:0	FLKEY[7:0]	<p>Flash Lock and Key Register.</p> <p>Write: This register provides a lock and key function for Flash erasures and writes. Flash writes and erases are enabled by writing 0xA5 followed by 0xF1 to the FLKEY register. Flash writes and erases are automatically disabled after the next write or erase is complete. If any writes to FLKEY are performed incorrectly, or if a Flash write or erase operation is attempted while these operations are disabled, the Flash will be permanently locked from writes or erasures until the next device reset. If an application never writes to Flash, it can intentionally lock the Flash by writing a non-0xA5 value to FLKEY from software.</p> <p>Read: When read, bits 1–0 indicate the current Flash lock state. 00: Flash is write/erase locked. 01: The first key code has been written (0xA5). 10: Flash is unlocked (writes/erases allowed). 11: Flash writes/erases disabled until the next reset.</p>

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SFR Definition 15.1. PMU0CF: Power Management Unit Configuration^{1,2,3}

Bit	7	6	5	4	3	2	1	0
Name	SLEEP	SUSPEND	CLEAR	RSTWK	RTCFWK	RTCAWK	PMATWK	CPT0WK
Type	W	W	W	R	R/W	R/W	R/W	R/W
Reset	0	0	0	Varies	Varies	Varies	Varies	Varies

SFR Page = 0x0; SFR Address = 0xB5

Bit	Name	Description	Write	Read
7	SLEEP	Sleep Mode Select	Writing 1 places the device in Sleep Mode.	N/A
6	SUSPEND	Suspend Mode Select	Writing 1 places the device in Suspend Mode.	N/A
5	CLEAR	Wake-up Flag Clear	Writing 1 clears all wake-up flags.	N/A
4	RSTWK	Reset Pin Wake-up Flag	N/A	Set to 1 if a glitch has been detected on \overline{RST} .
3	RTCFWK	SmaRTClock Oscillator Fail Wake-up Source Enable and Flag	0: Disable wake-up on SmaRTClock Osc. Fail. 1: Enable wake-up on SmaRTClock Osc. Fail.	Set to 1 if the SmaRTClock Oscillator has failed.
2	RTCAWK	SmaRTClock Alarm Wake-up Source Enable and Flag	0: Disable wake-up on SmaRTClock Alarm. 1: Enable wake-up on SmaRTClock Alarm.	Set to 1 if a SmaRTClock Alarm has occurred.
1	PMATWK	Port Match Wake-up Source Enable and Flag	0: Disable wake-up on Port Match Event. 1: Enable wake-up on Port Match Event.	Set to 1 if a Port Match Event has occurred.
0	CPT0WK	Comparator0 Wake-up Source Enable and Flag	0: Disable wake-up on Comparator0 rising edge. 1: Enable wake-up on Comparator0 rising edge.	Set to 1 if Comparator0 rising edge caused the last wake-up.

Notes:

1. Read-modify-write operations (ORL, ANL, etc.) should not be used on this register. Wake-up sources must be re-enabled each time the SLEEP or SUSPEND bits are written to 1.
2. The Low Power Internal Oscillator cannot be disabled and the MCU cannot be placed in Suspend or Sleep Mode if any wake-up flags are set to 1. Software should clear all wake-up sources after each reset and after each wake-up from Suspend or Sleep Modes.
3. PMU0 requires two system clocks to update the wake-up source flags after waking from Suspend mode. The wake-up source flags will read '0' during the first two system clocks following the wake from Suspend mode.

The 16-bit C8051F99x-C8051F98x CRC algorithm can be described by the following code:

```
unsigned short UpdateCRC (unsigned short CRC_acc, unsigned char CRC_input)
{
    unsigned char i;                                // loop counter

    #define POLY 0x1021

    // Create the CRC "dividend" for polynomial arithmetic (binary arithmetic
    // with no carries)
    CRC_acc = CRC_acc ^ (CRC_input << 8);

    // "Divide" the poly into the dividend using CRC XOR subtraction
    // CRC_acc holds the "remainder" of each divide
    //
    // Only complete this division for 8 bits since input is 1 byte
    for (i = 0; i < 8; i++)
    {
        // Check if the MSB is set (if MSB is 1, then the POLY can "divide"
        // into the "dividend")
        if ((CRC_acc & 0x8000) == 0x8000)
        {
            // if so, shift the CRC value, and XOR "subtract" the poly
            CRC_acc = CRC_acc << 1;
            CRC_acc ^= POLY;
        }
        else
        {
            // if not, just shift the CRC value
            CRC_acc = CRC_acc << 1;
        }
    }

    // Return the final remainder (CRC value)
    return CRC_acc;
}
```

Table 16.1 lists several input values and the associated outputs using the 16-bit C8051F99x-C8051F98x CRC algorithm:

Table 16.1. Example 16-bit CRC Outputs

Input	Output
0x63	0xBD35
0x8C	0xB1F4
0x7D	0x4ECA
0xAA, 0xBB, 0xCC	0x6CF6
0x00, 0x00, 0xAA, 0xBB, 0xCC	0xB166

20.2.5. Automatic Gain Control (Crystal Mode Only) and SmarTClock Bias Doubling

Automatic Gain Control allows the SmarTClock oscillator to trim the oscillation amplitude of a crystal in order to achieve the lowest possible power consumption. Automatic Gain Control automatically detects when the oscillation amplitude has reached a point where it safe to reduce the drive current, therefore, it may be enabled during crystal startup. It is recommended to enable Automatic Gain Control in most systems which use the SmarTClock oscillator in Crystal Mode. The following are recommended crystal specifications and operating conditions when Automatic Gain Control is enabled:

- ESR < 50 k Ω
- Load Capacitance < 10 pF
- Supply Voltage < 3.0 V
- Temperature > -20 °C

When using Automatic Gain Control, it is recommended to perform an oscillation robustness test to ensure that the chosen crystal will oscillate under the worst case condition to which the system will be exposed. The worst case condition that should result in the least robust oscillation is at the following system conditions: lowest temperature, highest supply voltage, highest ESR, highest load capacitance, and lowest bias current (AGC enabled, Bias Double Disabled).

To perform the oscillation robustness test, the SmarTClock oscillator should be enabled and selected as the system clock source. Next, the SYSCLK signal should be routed to a port pin configured as a push-pull digital output. The positive duty cycle of the output clock can be used as an indicator of oscillation robustness. As shown in Figure 20.2, duty cycles less than 55% indicate a robust oscillation. As the duty cycle approaches 60%, oscillation becomes less reliable and the risk of clock failure increases. Increasing the bias current (by disabling AGC) will always improve oscillation robustness and will reduce the output clock's duty cycle. This test should be performed at the worst case system conditions, as results at very low temperatures or high supply voltage will vary from results taken at room temperature or low supply voltage.

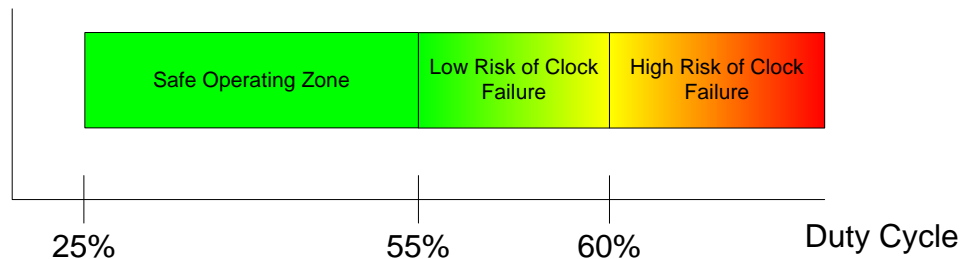


Figure 20.2. Interpreting Oscillation Robustness (Duty Cycle) Test Results

As an alternative to performing the oscillation robustness test, Automatic Gain Control may be disabled at the cost of increased power consumption (approximately 200 nA). Disabling Automatic Gain Control will provide the crystal oscillator with higher immunity against external factors which may lead to clock failure. Automatic Gain Control must be disabled if using the SmarTClock oscillator in self-oscillate mode.

Table 20.3 shows a summary of the oscillator bias settings. The SmarTClock Bias Doubling feature allows the self-oscillation frequency to be increased (almost doubled) and allows a higher crystal drive strength in crystal mode. High crystal drive strength is recommended when the crystal is exposed to poor environmental conditions such as excessive moisture. SmarTClock Bias Doubling is enabled by setting BIASX2 (RTC0XCN.5) to 1.

20.2.6. Missing SmarTClock Detector

The missing SmarTClock detector is a one-shot circuit enabled by setting MCLKEN (RTC0CN.6) to 1. When the SmarTClock Missing Clock Detector is enabled, OSCFAIL (RTC0CN.5) is set by hardware if SmarTClock oscillator remains high or low for more than 100 μ s.

A SmarTClock Missing Clock detector timeout can trigger an interrupt, wake the device from a low power mode, or reset the device. See Section “13. Interrupt Handler” on page 138, Section “15. Power Management” on page 162, and Section “18. Reset Sources” on page 181 for more information.

Note: The SmarTClock Missing Clock Detector should be disabled when making changes to the oscillator settings in RTC0XCN.

20.2.7. SmarTClock Oscillator Crystal Valid Detector

The SmarTClock oscillator crystal valid detector is an oscillation amplitude detector circuit used during crystal startup to determine when oscillation has started and is nearly stable. The output of this detector can be read from the CLKVLD bit (RTX0XCN.4).

Notes:

1. The CLKVLD bit has a blanking interval of 2 ms. During the first 2 ms after turning on the crystal oscillator, the output of CLKVLD is not valid.
2. This SmarTClock crystal valid detector (CLKVLD) is not intended for detecting an oscillator failure. The missing SmarTClock detector (CLKFAIL) should be used for this purpose.

20.3. SmarTClock Timer and Alarm Function

The SmarTClock timer is a 32-bit counter that, when running (RTC0TR = 1), is incremented every SmarTClock oscillator cycle. The timer has an alarm function that can be set to generate an interrupt, wake the device from a low power mode, or reset the device at a specific time. See Section “13. Interrupt Handler” on page 138, Section “15. Power Management” on page 162, and Section “18. Reset Sources” on page 181 for more information.

The SmarTClock timer includes an Auto Reset feature, which automatically resets the timer to zero one SmarTClock cycle after the alarm signal is deasserted. When using Auto Reset, the Alarm match value should always be set to 2 counts less than the desired match value. When using the LFO in combination with Auto Reset, the right-justified Alarm match value should be set to 4 counts less than the desired match value. Auto Reset can be enabled by writing a 1 to ALRM (RTC0CN.2).

20.3.1. Setting and Reading the SmarTClock Timer Value

The 32-bit SmarTClock timer can be set or read using the six CAPTUREn internal registers. Note that the timer does not need to be stopped before reading or setting its value. The following steps can be used to set the timer value:

1. Write the desired 32-bit set value to the CAPTUREn registers.
2. Write 1 to RTC0SET. This will transfer the contents of the CAPTUREn registers to the SmarTClock timer.
3. Operation is complete when RTC0SET is cleared to 0 by hardware.

The following steps can be used to read the current timer value:

1. Write 1 to RTC0CAP. This will transfer the contents of the timer to the CAPTUREn registers.
2. Poll RTC0CAP until it is cleared to 0 by hardware.
3. A snapshot of the timer value can be read from the CAPTUREn registers

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SFR Definition 22.3. SMB0ADR: SMBus Slave Address

Bit	7	6	5	4	3	2	1	0
Name	SLV[6:0]							GC
Type	R/W							R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xF4

Bit	Name	Function
7:1	SLV[6:0]	SMBus Hardware Slave Address. Defines the SMBus Slave Address(es) for automatic hardware acknowledgement. Only address bits which have a 1 in the corresponding bit position in SLVM[6:0] are checked against the incoming address. This allows multiple addresses to be recognized.
0	GC	General Call Address Enable. When hardware address recognition is enabled (EHACK = 1), this bit will determine whether the General Call Address (0x00) is also recognized by hardware. 0: General Call Address is ignored. 1: General Call Address is recognized.

SFR Definition 22.4. SMB0ADM: SMBus Slave Address Mask

Bit	7	6	5	4	3	2	1	0
Name	SLVM[6:0]							EHACK
Type	R/W							R/W
Reset	1	1	1	1	1	1	1	0

SFR Page = 0x0; SFR Address = 0xF5

Bit	Name	Function
7:1	SLVM[6:0]	SMBus Slave Address Mask. Defines which bits of register SMB0ADR are compared with an incoming address byte, and which bits are ignored. Any bit set to 1 in SLVM[6:0] enables comparisons with the corresponding bit in SLV[6:0]. Bits set to 0 are ignored (can be either 0 or 1 in the incoming address).
0	EHACK	Hardware Acknowledge Enable. Enables hardware acknowledgement of slave address and received data bytes. 0: Firmware must manually acknowledge all incoming address and data bytes. 1: Automatic Slave Address Recognition and Hardware Acknowledge is Enabled.

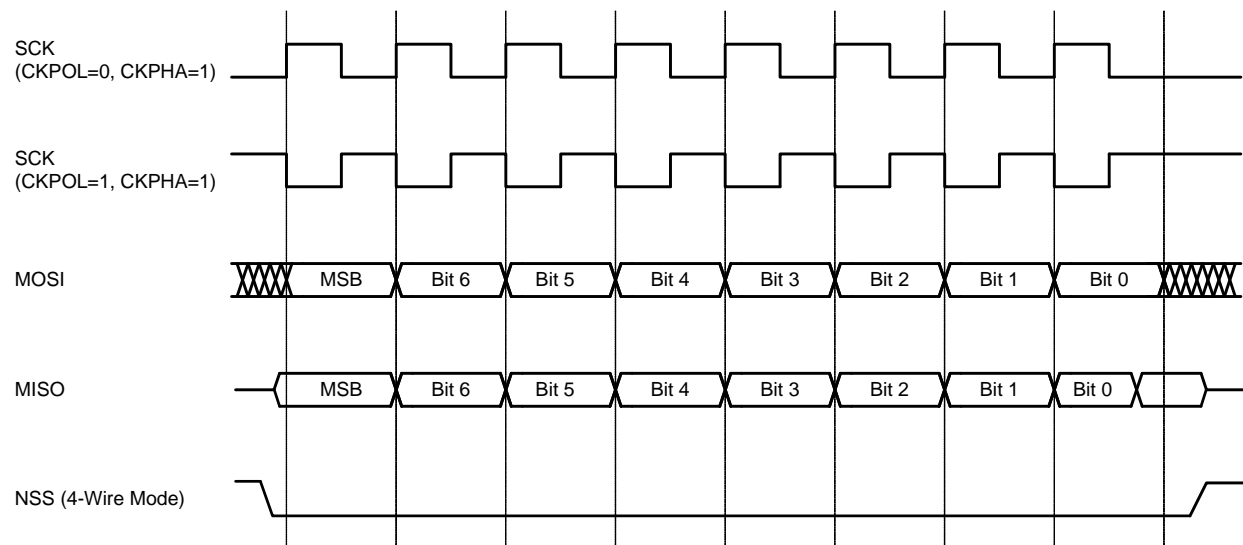


Figure 24.7. Slave Mode Data/Clock Timing (CKPHA = 1)

24.6. SPI Special Function Registers

SPI0 is accessed and controlled through four special function registers in the system controller: SPI0CN Control Register, SPI0DAT Data Register, SPI0CFG Configuration Register, and SPI0CKR Clock Rate Register. The four special function registers related to the operation of the SPI0 Bus are described in the following figures.

25.2.2. 8-bit Timers with Auto-Reload

When T2SPLIT is set, Timer 2 operates as two 8-bit timers (TMR2H and TMR2L). Both 8-bit timers operate in auto-reload mode as shown in Figure 25.5. TMR2RLH holds the reload value for TMR2L; TMR2RLH holds the reload value for TMR2H. The TR2 bit in TMR2CN handles the run control for TMR2H. TMR2L is always running when configured for 8-bit Mode.

Each 8-bit timer may be configured to use SYSCLK, SYSCLK divided by 12, SmarTClock divided by 8 or Comparator 0 output. The Timer 2 Clock Select bits (T2MH and T2ML in CKCON) select either SYSCLK or the clock defined by the Timer 2 External Clock Select bits (T2XCLK[1:0] in TMR2CN), as follows:

T2MH	T2XCLK[1:0]	TMR2H Clock Source
0	00	SYSClk / 12
0	01	SmaRTClock / 8
0	10	Reserved
0	11	Comparator 0
1	X	SYSClk

T2ML	T2XCLK[1:0]	TMR2L Clock Source
0	00	SYSClk / 12
0	01	SmaRTClock / 8
0	10	Reserved
0	11	Comparator 0
1	X	SYSClk

The TF2H bit is set when TMR2H overflows from 0xFF to 0x00; the TF2L bit is set when TMR2L overflows from 0xFF to 0x00. When Timer 2 interrupts are enabled (IE.5), an interrupt is generated each time TMR2H overflows. If Timer 2 interrupts are enabled and TF2LEN (TMR2CN.5) is set, an interrupt is generated each time either TMR2L or TMR2H overflows. When TF2LEN is enabled, software must check the TF2H and TF2L flags to determine the source of the Timer 2 interrupt. The TF2H and TF2L interrupt flags are not cleared by hardware and must be manually cleared by software.

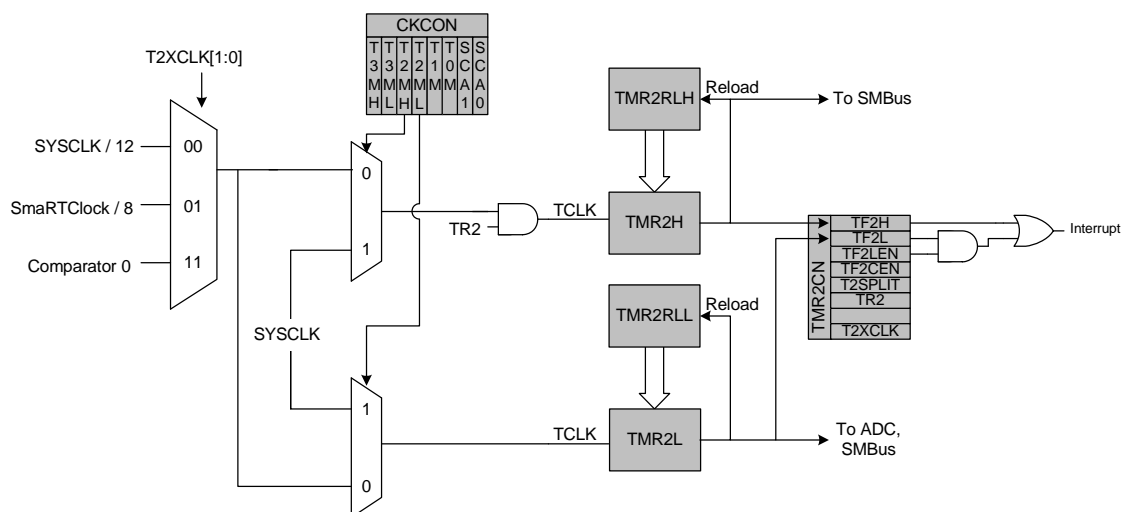


Figure 25.5. Timer 2 8-Bit Mode Block Diagram

C8051F99x-C8051F98x

SFR Definition 25.9. TMR2RLL: Timer 2 Reload Register Low Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR2RLL[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xCA

Bit	Name	Function
7:0	TMR2RLL[7:0]	Timer 2 Reload Register Low Byte. TMR2RLL holds the low byte of the reload value for Timer 2.

SFR Definition 25.10. TMR2RLH: Timer 2 Reload Register High Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR2RLH[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xCB

Bit	Name	Function
7:0	TMR2RLH[7:0]	Timer 2 Reload Register High Byte. TMR2RLH holds the high byte of the reload value for Timer 2.

26.3.6. 16-Bit Pulse Width Modulator Mode

A PCA module may also be operated in 16-Bit PWM mode. 16-bit PWM mode is independent of the other (8/9/10/11-bit) PWM modes. In this mode, the 16-bit capture/compare module defines the number of PCA clocks for the low time of the PWM signal. When the PCA counter matches the module contents, the output on CEXn is asserted high; when the 16-bit counter overflows, CEXn is asserted low. To output a varying duty cycle, new value writes should be synchronized with PCA CCFn match interrupts. 16-Bit PWM Mode is enabled by setting the ECOMn, PWMn, and PWM16n bits in the PCA0CPMn register. For a varying duty cycle, match interrupts should be enabled (ECCFn = 1 AND MATn = 1) to help synchronize the capture/compare register writes. If the MATn bit is set to 1, the CCFn flag for the module will be set each time a 16-bit comparator match (rising edge) occurs. The CF flag in PCA0CN can be used to detect the overflow (falling edge). The duty cycle for 16-Bit PWM Mode is given by Equation 26.4.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

$$\text{Duty Cycle} = \frac{(65536 - \text{PCA0CPn})}{65536}$$

Equation 26.4. 16-Bit PWM Duty Cycle

Using Equation 26.4, the largest duty cycle is 100% (PCA0CPn = 0), and the smallest duty cycle is 0.0015% (PCA0CPn = 0xFFFF). A 0% duty cycle may be generated by clearing the ECOMn bit to 0.

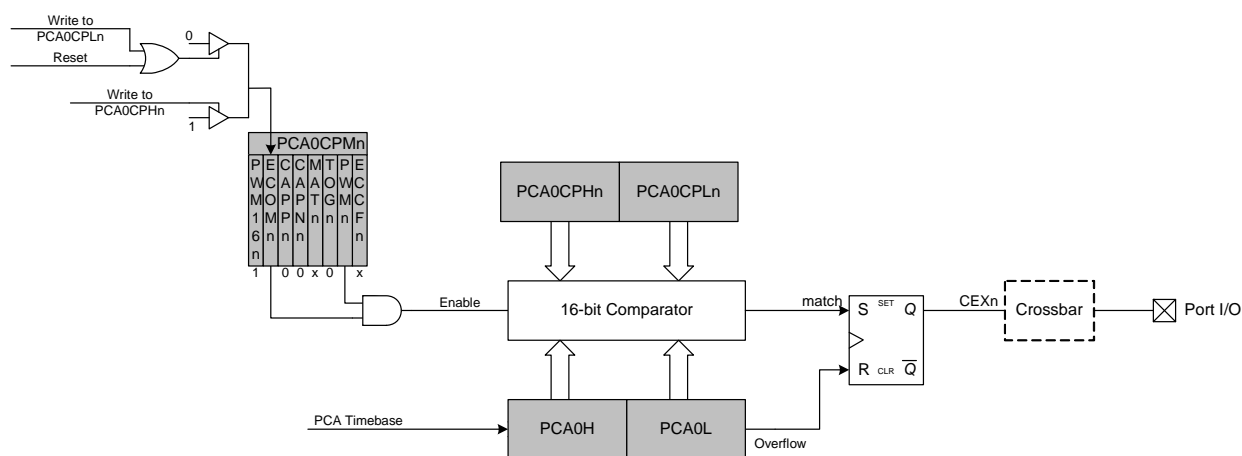


Figure 26.10. PCA 16-Bit PWM Mode

C8051F99x-C8051F98x

The 8-bit offset held in PCA0CPH2 is compared to the upper byte of the 16-bit PCA counter. This offset value is the number of PCA0L overflows before a reset. Up to 256 PCA clocks may pass before the first PCA0L overflow occurs, depending on the value of the PCA0L when the update is performed. The total offset is then given (in PCA clocks) by Equation 26.5, where PCA0L is the value of the PCA0L register at the time of the update.

$$Offset = (256 \times PCA0CPL2) + (256 - PCA0L)$$

Equation 26.5. Watchdog Timer Offset in PCA Clocks

The WDT reset is generated when PCA0L overflows while there is a match between PCA0CPH2 and PCA0H. Software may force a WDT reset by writing a 1 to the CCF2 flag (PCA0CN.2) while the WDT is enabled.

26.4.2. Watchdog Timer Usage

To configure the WDT, perform the following tasks:

1. Disable the WDT by writing a 0 to the WDTE bit.
2. Select the desired PCA clock source (with the CPS2–CPS0 bits).
3. Load PCA0CPL2 with the desired WDT update offset value.
4. Configure the PCA Idle mode (set CIDL if the WDT should be suspended while the CPU is in Idle mode).
5. Enable the WDT by setting the WDTE bit to 1.
6. Reset the WDT timer by writing to PCA0CPH2.

The PCA clock source and Idle mode select cannot be changed while the WDT is enabled. The watchdog timer is enabled by setting the WDTE or WDLCK bits in the PCA0MD register. When WDLCK is set, the WDT cannot be disabled until the next system reset. If WDLCK is not set, the WDT is disabled by clearing the WDTE bit.

The WDT is enabled following any reset. The PCA0 counter clock defaults to the system clock divided by 12, PCA0L defaults to 0x00, and PCA0CPL2 defaults to 0x00. Using Equation 26.5, this results in a WDT timeout interval of 256 PCA clock cycles, or 3072 system clock cycles. Table 26.3 lists some example timeout intervals for typical system clocks.

Table 26.3. Watchdog Timer Timeout Intervals¹

System Clock (Hz)	PCA0CPL2	Timeout Interval (ms)
24,500,000	255	32.1
24,500,000	128	16.2
24,500,000	32	4.1
3,062,500 ²	255	257
3,062,500 ²	128	129.5
3,062,500 ²	32	33.1
32,000	255	24576
32,000	128	12384
32,000	32	3168
Notes:		
1. Assumes SYSCLK/12 as the PCA clock source, and a PCA0L value of 0x00 at the update time.		
2. Internal SYSCLK reset frequency = Internal Oscillator divided by 8.		